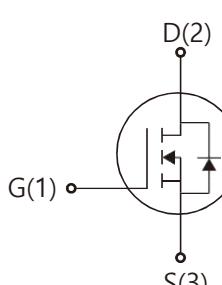


<p>Features:</p> <ul style="list-style-type: none"> <input type="checkbox"/> Low Intrinsic Capacitances. <input type="checkbox"/> Excellent Switching Characteristics. <input type="checkbox"/> Extended Safe Operating Area. <input type="checkbox"/> Unrivalled Gate Charge :$Q_g = 14\text{nC}$ (Typ.). <input type="checkbox"/> $V_{DSS} = 600\text{ V}$, $I_D = 7\text{A}$ <input type="checkbox"/> $R_{DS(on)} : 0.99\Omega$ (Max) @ $V_G = 10\text{V}$ <input type="checkbox"/> 100% Avalanche Tested 	 TO-220F   1.Gate (G) 2.Drain (D) 3.Source (S)
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Absolute Maximum Ratings (Ta=25°C unless otherwise noted)

Symbol	Parameter	Value	Unit
V_{DSS}	Drain-Source Voltage	600	V
I_D	Drain Current	$T_j = 25^\circ\text{C}$	7.0
		$T_j = 100^\circ\text{C}$	4.7
V_{GSS}	Gate-Source Voltage	± 25	V
E_{AS}	Single Pulse Avalanche Energy (note1)	119	mJ
I_{AR}	Avalanche Current (note2)	7.0	A
P_D	Power Dissipation ($T_j = 25^\circ\text{C}$)	45	W
T_j	Junction Temperature(Max)	150	$^\circ\text{C}$
T_{stg}	Storage Temperature	-55~+150	$^\circ\text{C}$
T_L	Maximum lead temperature for soldering purpose, 1/8' from case for 5 seconds	300	$^\circ\text{C}$

Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JC}$	Thermal Resistance,Junction to Case	-	2.78	$^\circ\text{C}/\text{W}$
$R_{\theta JA}$	Thermal Resistance,Junction to Ambient	-	50	$^\circ\text{C}/\text{W}$

Electrical Characteristics (Ta=25°C unless otherwise noted)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Unit
Off Characteristics						
BV _{DSS}	Drain-Source Breakdown Voltage	I _D =250μA , V _{GS} =0	600	-	-	V
△BV _{DSS} / △T _J	Breakdown Voltage Temperature Coefficient	I _D =250μA , Reference to 25°C	-	0.67	-	V/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =600V, V _{GS} =0V	-	-	10	μA
		V _{DS} =480V, T _j =125°C			100	
I _{GSSF}	Gate-body leakage Current, Forward	V _{GS} = +30V, V _{DS} =0V	-	-	100	nA
I _{GSSR}	Gate-body leakage Current, Reverse	V _{GS} = -30V, V _{DS} =0V	-	-	-100	
On Characteristics						
V _{GS(TH)}	Date Threshold Voltage	I _D =250μA,V _{DS} =V _{GS}	2	-	4	V
R _{DS(ON)}	Static Drain-Source On-Resistance	I _D =3.5A,V _{GS} =10V	-	0.89	0.99	Ω
Dynamic Characteristics						
C _{iss}	Input Capacitance	V _{DS} =50V , V _{GS} =0V, f=1.0MHz	-	363	-	pF
C _{oss}	Output Capacitance		-	24.6	-	
C _{rss}	Reverse Transfer Capacitance		-	1.1	-	
Switching Characteristics						
T _{d(on)}	Turn-On Delay Time	V _{DD} =300V , I _D =2.5A R _G =4.7Ω , V _{GS} =10V	-	7.2	-	nS
T _r	Turn-On Rise Time		-	10.3	-	
T _{d(of f)}	Turn-Off Delay Time		-	26.4	-	
T _f	Turn-Off Rise Time		-	12.6	-	
Q _g	Total Gate Charge	V _{DS} =480V,V _{GS} =10V , I _D =7A (Note3,4)	-	14	-	nC
Q _{gs}	Gate-Source Charge		-	2.7	-	
Q _{gd}	Gate-Drain Charge		-	7.7	-	
Drain-Source Diode Characteristics and Maximum Ratings						
I _s	Max. Diode Forward Current	-	-	-	7	A
I _{SM}	Max. Pulsed Forward Current	-	-	-	28	
V _{SD}	Diode Forward Voltage	I _D =7A	-	-	1.3	V
T _{rr}	Reverse Recovery Time	I _s =7A,V _{GS} =0V diF/dt=100A/ μs (Note3)	-	213	-	nS
Q _{rr}	Reverse Recovery Charge		-	1.8	-	μA

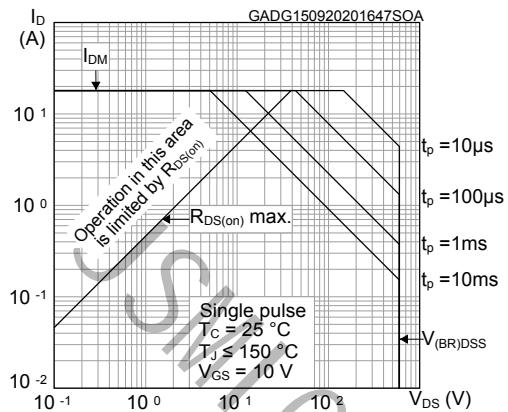
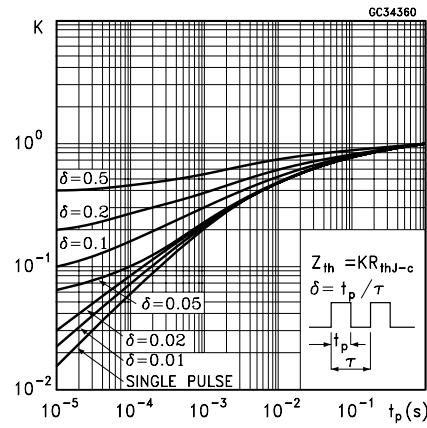
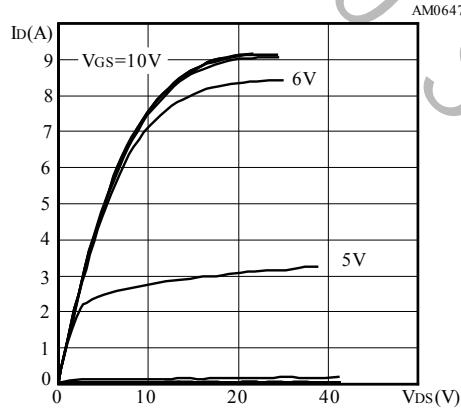
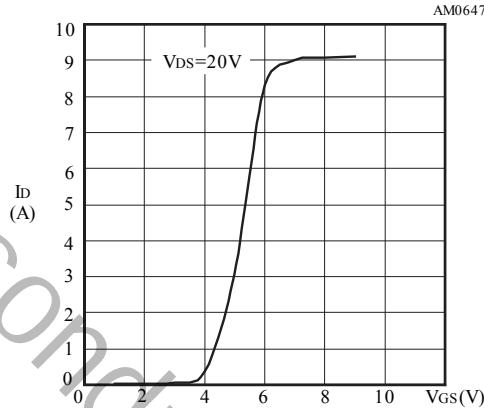
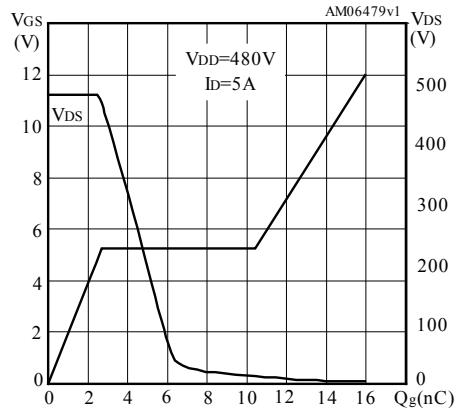
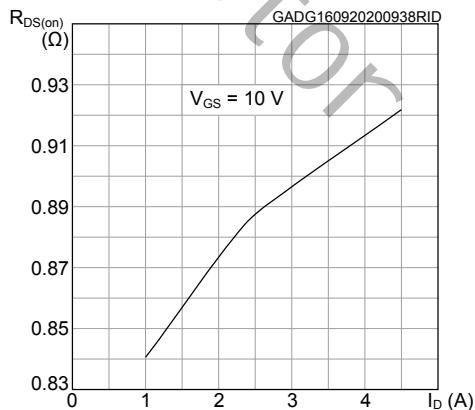
Notes : 1, L=0.5mH, IAS= 7A, VDD=50V, RG=25Ω, Starting TJ =25°C

2, Repetitive Rating : Pulse width limited by maximum junction temperature

3, Pulse Test : Pulse Width ≤ 300μs, Duty Cycle ≤ 2%

4, Essentially Independent of Operating Temperature

Typical Characteristics

Figure 1. Safe operating area

Figure 2. Thermal impedance

Figure 3. Output characteristics

Figure 4. Transfer characteristics

Figure 5. Gate charge vs gate-source voltage

Figure 6. Static drain-source on-resistance


Typical Characteristics (Continued)

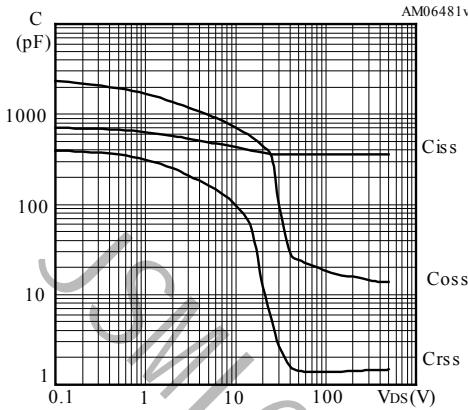
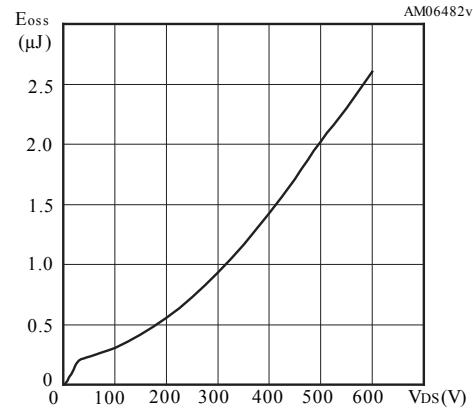
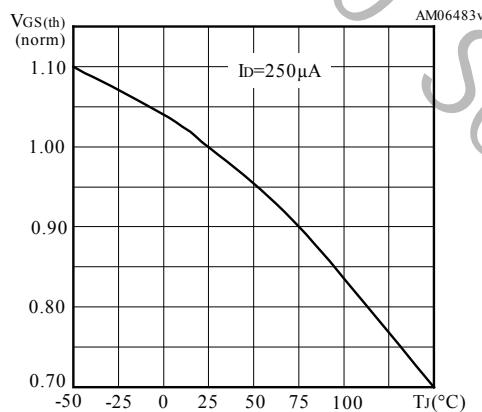
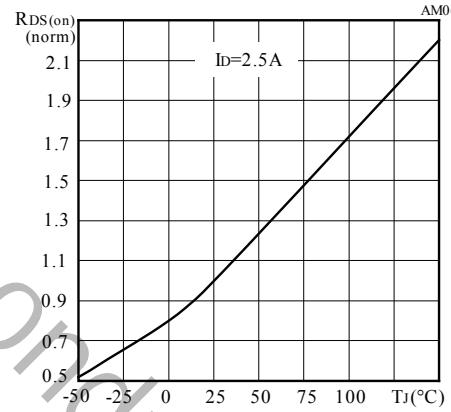
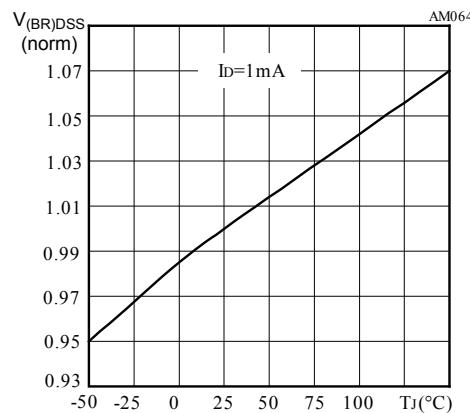
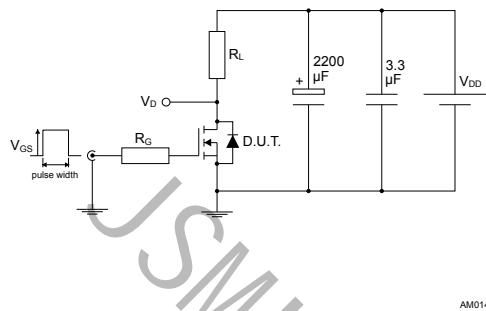
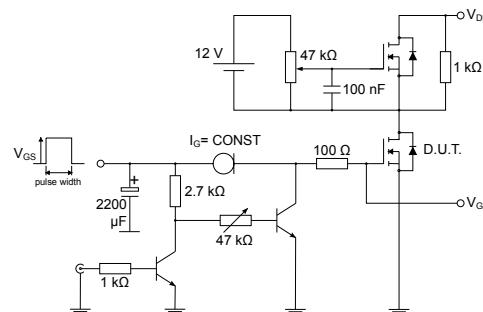
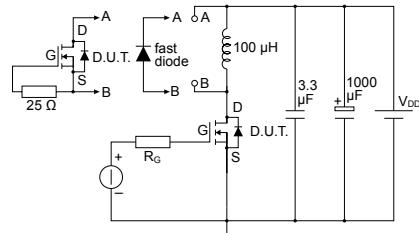
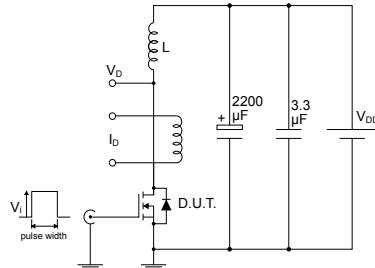
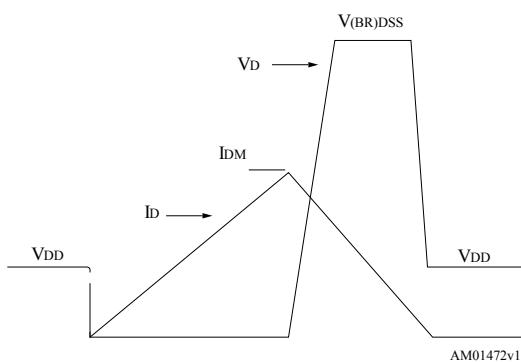
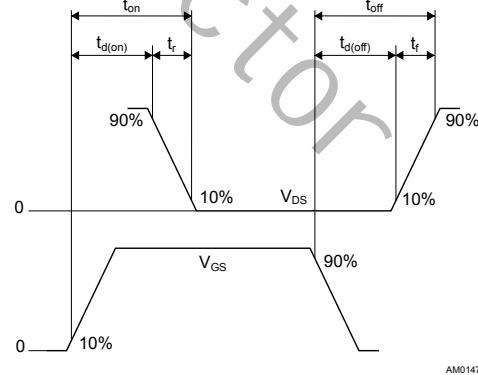
Figure 7. Capacitance variations

Figure 8. Output capacitance stored energy

Figure 9. Normalized gate threshold voltage vs temperature

Figure 10. Normalized on-resistance vs temperature

Figure 11. Normalized V(BR)DSS vs temperature


Figure 12. Test circuit for resistive load switching times

Figure 13. Test circuit for gate charge behavior

Figure 14. Test circuit for inductive load switching and diode recovery times

Figure 15. Unclamped inductive load test circuit

Figure 16. Unclamped inductive waveform

Figure 17. Switching time waveform


Package Dimension

TO-220F

Unit: mm

